江苏象化科技有限公司
JIANGSU ELEPHCHEM HOLDING LIMITED

Technical Date Sheet of Phenolic Resin for Electronic Materials

Product name: Phenolic Resin
CAS NO.: 9003-35-4

Technical Data of Phenolic Resin for Electronic Materials

Items	Specifications
Model	Y1001
Appearance	Light yellow liquid
Solid content (%/150℃/1h)	65~70
Viscosity (mpa.s, 25℃)	1000～1300
Free Phenol	<0.5
Free Aldehyde Content	≤0.5%
Softening Point (℃)	95~105
Solvent	Butanone

Application:

The products are used in chip process adhesives, photoresists, semiconductor packaging molding compounds, copper clad laminates, prepregs, PCB inks, epoxy powder coatings, electronic encapsulation materials, potting compounds, conductive silver pastes and other fields, and are ultimately used in smart cars, mobile phones, notebooks, computers, white appliances, Internet terminals and Internet servers, signal base stations and other aspects. They are the physical foundation for the modern electronic information industry.

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Packing:

Paper-plastic composite packaging lined with PP bags, 25kg/bag.

Storage:

Store in a dry, cool, and well-ventilated place. Be careful not to break the barrel. If damaged, use immediately. Store below 15°C for 12 months.

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